

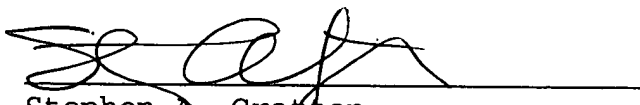
REMARKS

Claims 78-108 of the present continuation application are directed to a method for fabricating a semiconductor component, such as a semiconductor package 130 (Figure 8). The method includes the step of providing a substrate 10 (Figure 1A) having a first side (face side 14-Figure 1A) and a second side (backside 16-Figure 1A). The method also includes the step of forming a plurality of openings 30 (Figure 1B) in the substrate 10, extending from the first side (face side 14-Figure 1A) to the second side (backside 16-Figure 1A). In addition, the method includes the step of forming conductive members 34 (Figure 1D) in the openings 30 by depositing a solder metal into the openings 30 using capillary action or a solder wave (page 12, lines 22-25 of the specification).

Also being submitted with this continuation application is an Information Disclosure Statement. Favorable consideration and allowance of claims 78-108 is respectfully requested. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

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Respectfully submitted:



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